

# Octal 3-State Inverting D Flip-Flop High-Performance Silicon-Gate CMOS

The MC54/74HC533A is identical in pinout to the LS533. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

These latches appear transparent to data (i.e., the outputs change asynchronously) when Latch Enable is high. The Data appears at the outputs in inverted form. When Latch Enable goes low, data meeting the setup and hold time becomes latched.

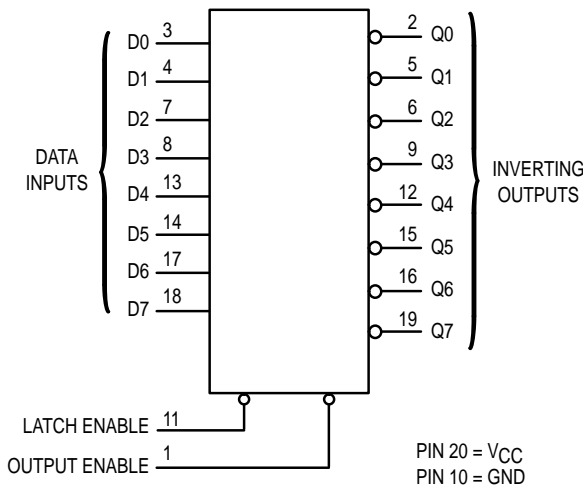
The Output Enable input does not affect the state of the latches, but when Output Enable is high, all device outputs are forced to the high-impedance state. Thus, data may be latched even when the outputs are not enabled.

The HC533A is identical in function to the HC563 but has the data inputs on the opposite side of the package from the outputs to facilitate PC board layout.

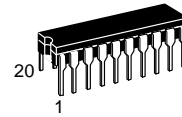
This device is similar in function to the HC373A, which has noninverting outputs.

- Output Drive Capability: 15 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0  $\mu$ A
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- Chip Complexity: 256 FETs or 64 Equivalent Gates

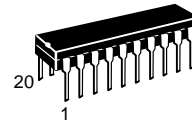
**LOGIC DIAGRAM**



## MC54/74HC533A



**J SUFFIX**  
CERAMIC PACKAGE  
CASE 732-03



**N SUFFIX**  
PLASTIC PACKAGE  
CASE 738-03

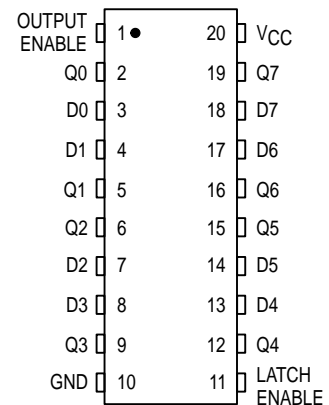


**DW SUFFIX**  
SOIC PACKAGE  
CASE 751D-04

**ORDERING INFORMATION**

MC54HCXXXAJ	Ceramic
MC74HCXXXAN	Plastic
MC74HCXXXADW	SOIC

**PIN ASSIGNMENT**



**FUNCTION TABLE**

Inputs			Output
Output Enable	Latch Enable	D	Q
L	H	H	L
L	H	L	H
L	L	X	No Change
H	X	X	Z

X = Don't Care  
Z = High Impedance



# MC54/74HC533A

## MAXIMUM RATINGS\*

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	- 0.5 to + 7.0	V
V <sub>in</sub>	DC Input Voltage (Referenced to GND)	- 1.5 to V <sub>CC</sub> + 1.5	V
V <sub>out</sub>	DC Output Voltage (Referenced to GND)	- 0.5 to V <sub>CC</sub> + 0.5	V
I <sub>in</sub>	DC Input Current, per Pin	± 20	mA
I <sub>out</sub>	DC Output Current, per Pin	± 35	mA
I <sub>CC</sub>	DC Supply Current, V <sub>CC</sub> and GND Pins	± 75	mA
P <sub>D</sub>	Power Dissipation in Still Air, Plastic or Ceramic DIP† SOIC Package†	750 500	mW
T <sub>stg</sub>	Storage Temperature	- 65 to + 150	°C
T <sub>L</sub>	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package) (Ceramic DIP)	260 300	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V<sub>in</sub> and V<sub>out</sub> should be constrained to the range GND ≤ (V<sub>in</sub> or V<sub>out</sub>) ≤ V<sub>CC</sub>. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V<sub>CC</sub>). Unused outputs must be left open.

\* Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

† Derating — Plastic DIP: - 10 mW/°C from 65° to 125°C  
Ceramic DIP: - 10 mW/°C from 100° to 125°C  
SOIC Package: - 7 mW/°C from 65° to 125°C

For high frequency or heavy load considerations, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	2.0	6.0	V
V <sub>in</sub> , V <sub>out</sub>	DC Input Voltage, Output Voltage (Referenced to GND)	0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature, All Package Types	- 55	+ 125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time (Figure 1)	V <sub>CC</sub> = 2.0 V 0 V <sub>CC</sub> = 4.5 V 0 V <sub>CC</sub> = 6.0 V 0	1000 500 400	ns

## DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V <sub>CC</sub> V	Guaranteed Limit			Unit
				- 55 to 25°C	≤ 85°C	≤ 125°C	
V <sub>IH</sub>	Minimum High-Level Input Voltage	V <sub>out</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V  I <sub>out</sub>   ≤ 20 μA	2.0	1.5	1.5	1.5	V
			4.5	3.15	3.15	3.15	
			6.0	4.2	4.2	4.2	
V <sub>IL</sub>	Maximum Low-Level Input Voltage	V <sub>out</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V  I <sub>out</sub>   ≤ 20 μA	2.0	0.5	0.5	0.5	V
			4.5	1.35	1.35	1.35	
			6.0	1.8	1.8	1.8	
V <sub>OH</sub>	Minimum High-Level Output Voltage	V <sub>in</sub> = V <sub>IH</sub> or V <sub>IL</sub>  I <sub>out</sub>   ≤ 20 μA	2.0	1.9	1.9	1.9	V
			4.5	4.4	4.4	4.4	
			6.0	5.9	5.9	5.9	V
			4.5	3.98	3.84	3.7	
6.0	5.48	5.34	5.2				
V <sub>OL</sub>	Maximum Low-Level Output Voltage	V <sub>in</sub> = V <sub>IH</sub> or V <sub>IL</sub>  I <sub>out</sub>   ≤ 20 μA	2.0	0.1	0.1	0.1	V
			4.5	0.1	0.1	0.1	
			6.0	0.1	0.1	0.1	V
			4.5	0.26	0.33	0.4	
6.0	0.26	0.33	0.4				
I <sub>in</sub>	Maximum Input Leakage Current	V <sub>in</sub> = V <sub>CC</sub> or GND	6.0	± 0.1	± 1.0	± 1.0	μA

**DC ELECTRICAL CHARACTERISTICS** (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V <sub>CC</sub> V	Guaranteed Limit			Unit
				– 55 to 25°C	≤ 85°C	≤ 125°C	
I <sub>OZ</sub>	Maximum Three-State Leakage Current	Output in High-Impedance State V <sub>in</sub> = V <sub>IL</sub> or V <sub>IH</sub> V <sub>out</sub> = V <sub>CC</sub> or GND	6.0	± 0.5	± 5.0	± 10	μA
I <sub>CC</sub>	Maximum Quiescent Supply Current (per Package)	V <sub>in</sub> = V <sub>CC</sub> or GND  I <sub>out</sub>   = 0 μA	6.0	4.0	40	160	μA

NOTE: Information on typical parametric values can be found in Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

**AC ELECTRICAL CHARACTERISTICS** (C<sub>L</sub> = 50 pF, Input t<sub>r</sub> = t<sub>f</sub> = 6.0 ns)

Symbol	Parameter	Fig.	V <sub>CC</sub> V	Guaranteed Limit			Unit
				– 55 to 25°C	≤ 85°C	≤ 125°C	
t <sub>PLH</sub> t <sub>PHL</sub>	Maximum Propagation Delay, Input D to Q	1, 5	2.0 4.5 6.0	125 25 21	155 31 26	190 38 32	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Maximum Propagation Delay, Latch Enable to Q	2, 5	2.0 4.5 6.0	125 25 21	155 31 26	190 38 32	ns
t <sub>PLZ</sub> t <sub>PHZ</sub>	Maximum Propagation Delay, Output Enable to Q	3, 6	2.0 4.5 6.0	150 30 26	190 38 33	225 45 38	ns
t <sub>PZL</sub> t <sub>PZH</sub>	Maximum Propagation Delay, Output Enable to Q	3, 6	2.0 4.5 6.0	150 30 26	190 38 33	225 45 38	ns
t <sub>TLH</sub> t <sub>THL</sub>	Maximum Output Transition Time, Any Output	1, 5	2.0 4.5 6.0	75 15 13	95 19 16	110 22 19	ns
C <sub>in</sub>	Maximum Input Capacitance			10	10	10	pF
C <sub>out</sub>	Maximum Tri-State Output Capacitance (Output in Hi-Impedance State)			15	15	15	pF

NOTE: For propagation delays with loads other than 50 pF, and information on typical parametric values, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

C <sub>PD</sub>	Power Dissipation Capacitance (Per Enabled Output)*	Typical @ 25°C, V <sub>CC</sub> = 5.0 V	
		36	
		pF	

\* Used to determine the no-load dynamic power consumption: P<sub>D</sub> = C<sub>PD</sub> V<sub>CC</sub><sup>2</sup>f + I<sub>CC</sub> V<sub>CC</sub>. For load considerations, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

MC54/74HC533A

**TIMING REQUIREMENTS** ( $C_L = 50 \text{ pF}$ , Input  $t_r = t_f = 6.0 \text{ ns}$ )

Symbol	Parameter	Fig.	VCC Volts	Guaranteed Limit						Unit	
				- 55 to 25°C		≤ 85°C		≤ 125°C			
				Min	Max	Min	Max	Min	Max		
$t_{su}$	Minimum Setup Time, Input D to Latch Enable	4	2.0 4.5 6.0	25 5.0 5.0		30 6.0 6.0		40 8.0 7.0		ns	
$t_h$	Minimum Hold Time, Latch Enable to Input D	4	2.0 4.5 6.0	5.0 5.0 5.0		5.0 5.0 5.0		5.0 5.0 5.0		ns	
$t_w$	Minimum Pulse Width, Latch Enable	2	2.0 4.5 6.0	60 12 10		75 15 13		90 18 15		ns	
$t_r, t_f$	Maximum Input Rise and Fall Times	1	2.0 4.5 6.0		1000 500 400		1000 500 400		1000 500 400		ns

**SWITCHING WAVEFORMS**

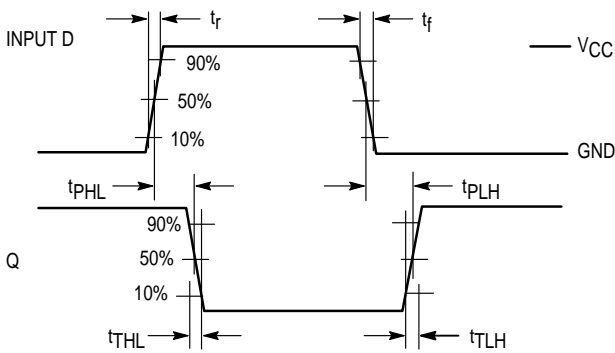


Figure 1.

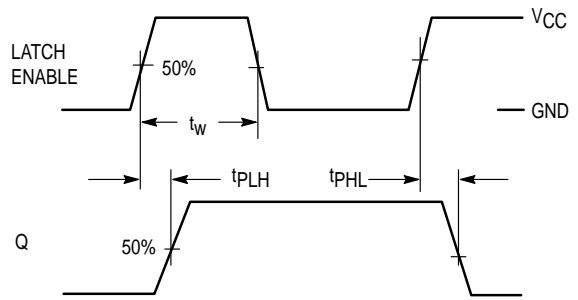


Figure 2.

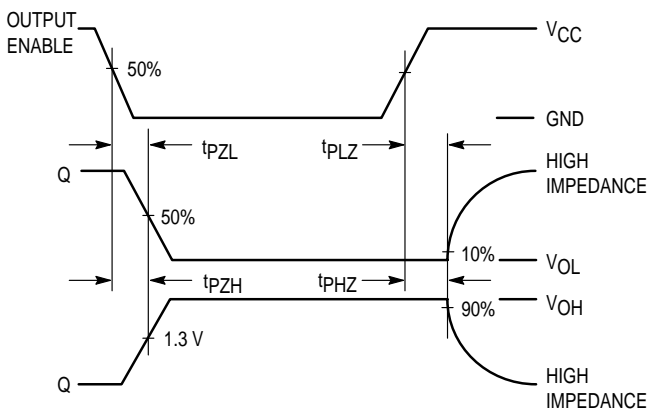


Figure 3.

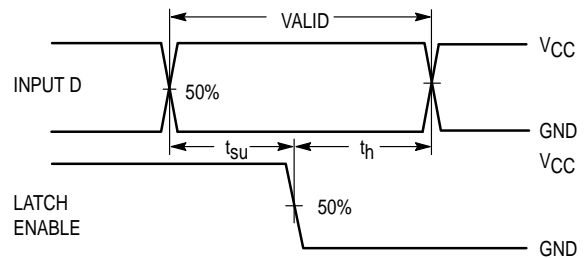
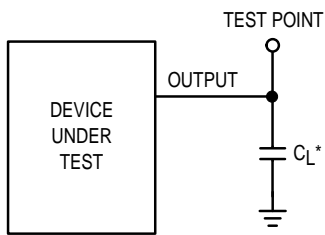


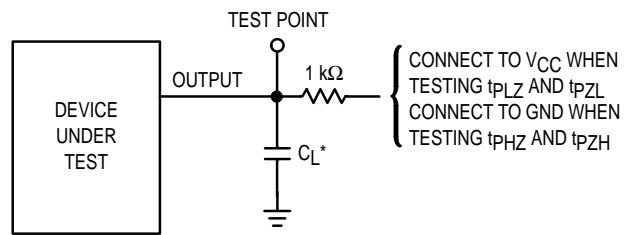
Figure 4.

TEST CIRCUITS



\* Includes all probe and jig capacitance

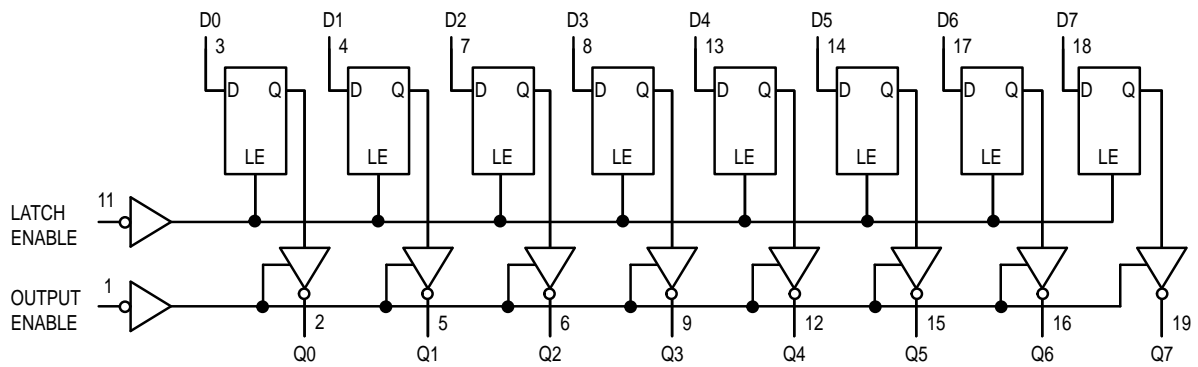
Figure 5.



\* Includes all probe and jig capacitance

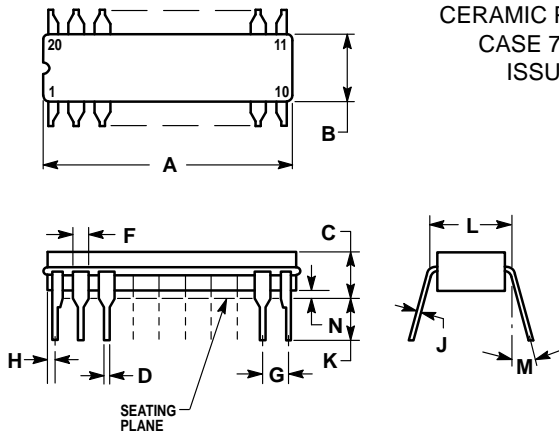
Figure 6.

EXPANDED LOGIC DIAGRAM



OUTLINE DIMENSIONS

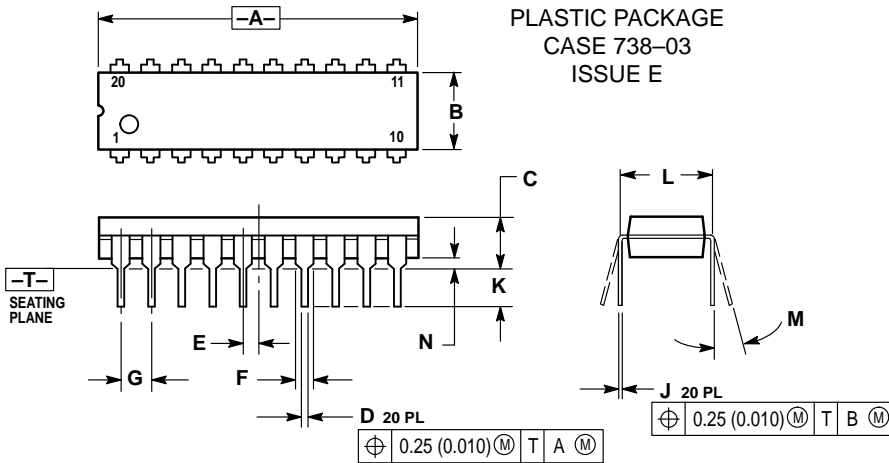
**J SUFFIX**  
**CERAMIC PACKAGE**  
**CASE 732-03**  
**ISSUE E**



- NOTES:
- LEADS WITHIN 0.25 (0.010) DIAMETER, TRUE POSITION AT SEATING PLANE, AT MAXIMUM MATERIAL CONDITION.
  - DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  - DIMENSIONS A AND B INCLUDE MENISCUS.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	23.88	25.15	0.940	0.990
B	6.60	7.49	0.260	0.295
C	3.81	5.08	0.150	0.200
D	0.38	0.56	0.015	0.022
F	1.40	1.65	0.055	0.065
G	2.54 BSC		0.100 BSC	
H	0.51	1.27	0.020	0.050
J	0.20	0.30	0.008	0.012
K	3.18	4.06	0.125	0.160
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.25	1.02	0.010	0.040

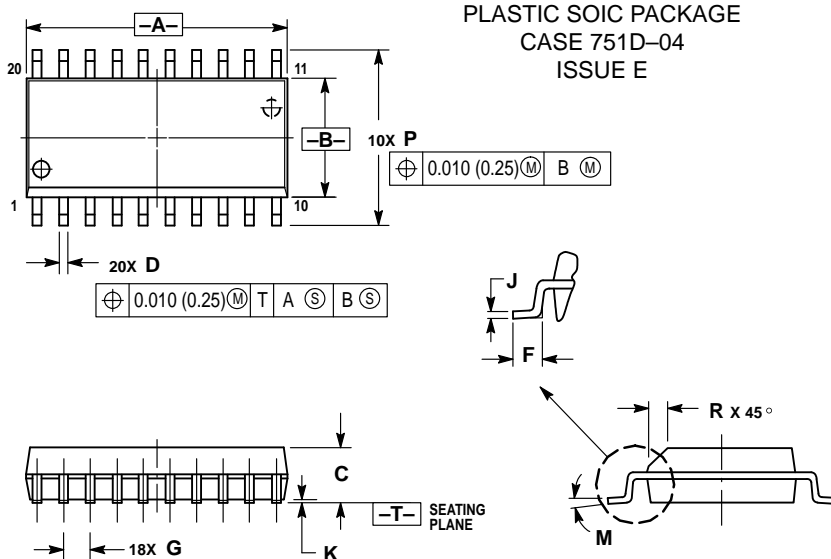
**N SUFFIX**  
**PLASTIC PACKAGE**  
**CASE 738-03**  
**ISSUE E**



- NOTES:
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  - CONTROLLING DIMENSION: INCH.
  - DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
  - DIMENSION B DOES NOT INCLUDE MOLD FLASH.


DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.010	1.070	25.66	27.17
B	0.240	0.260	6.10	6.60
C	0.150	0.180	3.81	4.57
D	0.015	0.022	0.39	0.55
E	0.050 BSC		1.27 BSC	
F	0.050	0.070	1.27	1.77
G	0.100 BSC		2.54 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.140	2.80	3.55
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

**DW SUFFIX**  
**PLASTIC SOIC PACKAGE**  
**CASE 751D-04**  
**ISSUE E**



- NOTES:
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  - CONTROLLING DIMENSION: MILLIMETER.
  - DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
  - MAXIMUM MOLD PROTRUSION 0.150 (0.006) PER SIDE.
  - DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	12.65	12.95	0.499	0.510
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

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MC54/74HC533A/D

